

# 8329TFF



## Fast Cure Thermal Glue

8329TFF is a 2-part, flame retardant, thermally conductive epoxy adhesive with a 5-minute working time. It is an off white, smooth, thixotropic paste that cures to form a hard, durable polymer that is thermally conductive, yet electrically insulating.

This thermal glue is often used to bond heatsinks to CPUs, LEDs and other electronics components.

This product has a very short working time. For a longer working time, use 8349TFM or 8329TFS.



## Features & Benefits

- High thermal conductivity
- Flame retardant—UL 94V-0 registered (File # E334302)
- 1:1 mix ratio
- Provides strong electrical insulation
- Low CTE prior  $T_g$
- High tensile and compressive strength
- Bonds well to a wide variety of substances
- Strong resistance to humidity, salt water, mild bases, and aliphatic hydrocarbons

## Available Packaging

Cat. No.	Packaging	Net Vol.	Net Wt.
8329TFF-25ML	Dual Syringe	25 mL	40.1 g
8329TFF-50ML	Dual Cartridge	45 mL	72.3 g

## Contact Information

MG Chemicals, 1210 Corporate Drive  
Burlington, Ontario, Canada L7L 5R6

Email: [support@mgchemicals.com](mailto:support@mgchemicals.com)

Phone: North America: +(1)800-340-0772

International: +(1) 905-331-1396

Europe: +(44)1663 362888

## Cured Properties

Resistivity	$7.9 \times 10^{12} \Omega \cdot \text{cm}$
Hardness	82 D
Tensile Strength	13 N/mm <sup>2</sup>
Compressive Strength	65 N/mm <sup>2</sup>
Lap Shear (stainless steel)	7.1 N/mm <sup>2</sup>
(aluminum)	8.3 N/mm <sup>2</sup>
Glass Transition Temperature ( $T_g$ )	25 °C
CTE Prior $T_g$	34 ppm/°C
CTE After $T_g$	146 ppm/°C
Thermal Conductivity @ 25 °C	0.8 W/(m·K)
Service Temperature Range	-40–150 °C

## Usage Parameters

Working Time	5 min
Mix Ratio by Volume	1:1
Mix Ratio by Weight	1:0.9

## Uncured Properties

Mixed Density	1.6 g/mL
Viscosity @ 25 °C	(A) 72 Pa·s
	(B) 110 Pa·s

## Application Instructions

Read the product SDS and Application Guide for more detailed instructions before using this product (downloadable at [www.mgchemicals.com](http://www.mgchemicals.com)).

## Recommended Preparation

Clean the substrate with Isopropyl Alcohol, MG #824, so the surface is free of oils, dust, and other residues.

## Syringe or Cartridge

1. Twist and remove the cap from the syringe or cartridge. Do not discard cap.
2. If nozzle is blocked, clean any hardened material on both the inside and outside using a needle and paper towel.
3. Dispense a small amount to ensure even flow of both parts. A manual or pneumatic dispensing gun is required for a 50 mL cartridge.
4. (Optional) Attach a static mixer.
  - a. Dispense and discard 3 to 5 mL of the product to ensure a homogeneous mixture.
  - b. After use, dispose of static mixer.
5. Without a static mixer, dispense material on a mixing surface or container, and thoroughly mix parts A and B together.
6. To stop the flow, pull back on the plunger.
7. Clean nozzle to prevent contamination and material buildup.
8. Re-place the cap on the cartridge or syringe or cartridge.

## Dispensing Accessories

Consult the table below for accessory selection. See the Dispensing Accessories Application Guide for usage instructions. 8MT-50-FT should only be used with a pneumatic dispenser.

Cat. No.	Dispensing Gun	Static Mixer
8329TFF-25ML	N/A	N/A
8329TFF-50ML	8DG-50-1-1	8MT-50, 8MT-50-FT

## Cure Instructions

Allow to cure at room temperature for 4 hours, or cure the adhesive in an oven at one of these time/temperature options:

<b>Temperature</b>	65 °C	80 °C
<b>Time</b>	15 minutes	10 minutes

## Storage and Handling

Store between 16 and 27 °C in a dry area, away from sunlight (see SDS). To maximize shelf life, recap product firmly when not in use.

## Disclaimer

This information is believed to be accurate. It is intended for professional end-users who have the skills required to evaluate and use the data properly. M.G. Chemicals Ltd. does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.